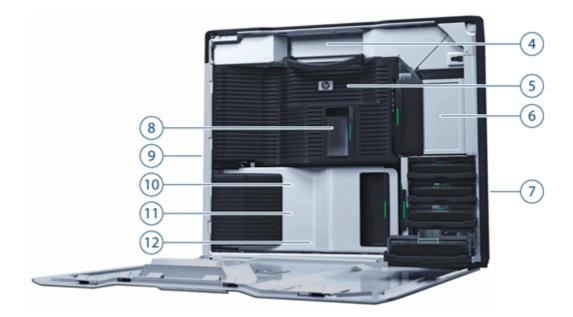
Overview

HP recommends Windows Vista®
Business



- 1. 3 External 5.25" Bays
- 2. Power Button
- 3. Front I/O: 3 USB 2.0, 1 IEEE 1394a, 1 Headphone out, 1 Microphone in

Overview



- 4. Choice of 850W, 85% or 1110W, 89% Power Supplies
- 5. 12 DIMM Slots for DDR3 ECC Memory
- 6. 3 External 5.25" Bays
- 7. 4 Internal 3.5" Bays
- 8. 2 Quad Core Intel 5500 Series Processors

- 9. Rear I/O: 1 IEEE 1394a, 6 USB 2.0, 1 serial, PS/2 keyboard/mouse
 - 2 RJ-45 to Integrated Gigabit LAN
 - 1 Audio Line In, 1 Audio Line Out, 1 Microphone In
- 10. 2 PCle x16 Gen2 Slots
- 2 PCle x8 Gen2, 1 PCle x4 Gen2, 1 PCle x4 Gen1, 1 PCl Slot
- 12 3 Internal USB 2.0 ports

Form Factor	Rackable Minitower					
Compatible Operating	Genuine Windows Vista® Business 32-bit*					
Systems	Genuine Windows Vista® Business 64-bit*					
	Genuine Windows Vista® Business 32-bit with downgrade to Windows® XP Professional 32-bit custom installed**					
	Genuine Windows Vista® Business 64-bit with downgrade to Windows® XP Professional x64 custom installed**					
	HP Linux Installer Kit for Linux (includes drivers for both 32-bit & 64-bit OS versions of Red Hat Enterprise Linux WS4 and WS5 - see: http://www.hp.com/workstations/software/linux)					
	For detailed OS/hardware support information for Linux, see:					
	http://www.hp.com/support/linux_hardware_matrix					
	*Certain Windows Vista product features require advanced or additional hardware. See http://www.microsoft.com/windowsvista/getready/hardwarereqs.mspx and http://www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade					
	Advisor can help you determine which features of Windows Vista will run on your computer. To download					
	the tool, visit http://www.windowsvista.com/upgradeadvisor.					
	**Windows Vista Business disk may also be included for future upgrade if desired. To qualify for this					
	downgrade an end user must be a business (including governmental or educational institutions) and is					
	expected to order at least 25 customer systems with the same custom image.					

Overview

Available Processors

Intel® Xeon® Processor W5580 QC 3.20 GHz, 130W, 8M Cache, 6.4GT/sec QPI, DDR3 1333MHz, HT, Turbo

Intel Xeon Processor X5570 QC 2.93 GHz, 95W, 8M cache, 6.4GT/s QPI, DDR3 1333MHz, HT, Turbo Intel Xeon Processor X5560 QC 2.80 GHz, 95W, 8M cache, 6.4GT/s QPI, DDR3 1333MHz, HT, Turbo Intel Xeon Processor X5550 QC 2.66 GHz, 95W, 8M cache, 6.4GT/s QPI, DDR3 1333MHz, HT, Turbo Intel Xeon Processor E5540 QC 2.53 GHz, 80W, 8M cache, 5.86GT/s QPI, DDR3 1066MHz, HT, Turbo

Intel Xeon Processor E5530 QC 2.40 GHz, 80W, 8M cache, 5.86GT/s QPI, DDR3 1066MHz, HT, Turbo

Intel Xeon Processor E5520 QC 2.26 GHz, 80W, 8M cache, 5.86GT/s QPI, DDR3 1066MHz, HT, Turbo

Intel Xeon Processor E5506 QC 2.13 GHz, 80W, 4M cache, 4.8GT/s QPI, DDR3 800 Intel Xeon Processor E5504 QC 2.00 GHz, 80W, 4M cache, 4.8GT/s QPI, DDR3 800

Available Processor Disclaimers

When ordering two processors, the second processor must be the same as the first. Processor numbers differentiate features within each processor family, not across different processor families. See: http://www.intel.com/products/processor number/ for details.

Quad-Core technologies are designed to improve performance of multithreaded software products and hardware-aware multitasking operating systems and may require appropriate operating system software for full benefits; check with software provider to determine suitability; Not all customers or software applications will necessarily benefit from use of these technologies.

64-bit computing on Intel® 64 architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers, and applications enabled for Intel® 64 architecture. Processors will not operate (including 32-bit operation) without an Intel® 64 architecture-enabled BIOS. Performance will vary depending on your hardware and software configurations. See: http://www.intel.com/info/em64t for more information.

Intel's numbering is not a measurement of higher performance.

Additional Details

Intel® Nehalem Architecture

Up to 6.4GT/s QPI support

3-channel 800/1066/1333 MHz DDR3* memory subsystem

Up to 192GB memory capacity

PCI Express I/O and PCIe x16 Gen2 graphics

Dual integrated Broadcom 5764 Gigabit LAN on Motherboard (LOM)

6 channels of Serial ATA (SATA) and 8 channels of Serial Attached SCSI (SAS) 3.0 Gb/s natively supported internally; SATA RAID level 0, 1, 5 and 10 and SAS RAID** level 0, 1, 10 available on motherboard*

SATA optical drives

High Definition integrated audio with internal speaker

Choice of 850W 85% efficient or 1110W 89% efficient power supply

ENERGY STAR® qualification and energy-saving features available on selected configurations (Not supported by Linux)

Protected by HP Services, including a 3 years parts, 3 years labor, and 3 years onsite service (3/3/3) standard warranty. Terms and conditions vary by country. Certain restrictions and exclusions apply.

*Each processor supports up to 3 channels of DDR3 memory. To realize full performance at least 1 DIMM must be inserted into each channel. To get full 6 channel support, 2 processors MUST be installed. **SATA hardware RAID is not supported on Linux systems. The Linux kernel, with built-in software RAID, provides excellent functionality and performance. It is a good alternative to hardware-based RAID. Please visit http://h20000.www2.hp.com/bc/docs/support/SupportManual/c00060684/c00060684.pdf for RAID capabilities with Linux.



Overview

Color	Black/Silver				
I/O Slots (see system	• 2 PCI Express Ge	en2 x16 slots (full-length, full-height)			
board section for more		• 2 PCI Express Gen2 x8 slots - with x8 connectors (full-length, full-height)			
details)	• 1 PCI Express Ge	1 PCI Express Gen2 x4 slot - with x8 connector (half-length, full-height)			
	• 1 PCI Express Ge	en1 x4 slot - with x8 connector (full-length, full-height)			
		IHz slot, (full-length, full-height)			
		ly slot, supporting cards which mount only to the I/O bulkhead and not the			
	motherboard (ha	lf-length, full-height)			
	 The PCle x8 conr 	nectors are open ended, allowing a PCIe x16 card to be seated in the slot.			
Bays (see storage section	Total Bays = 7				
for more details)					
Internal Bays	4 internal 3.5" bays (4 v	with acoustic dampening rail assemblies)			
External Bays	3 external 5.25" bays				
	Top bay device depth li	mit: 175mm			
	Middle bay device dept	h limit: 206mm			
	Bottom bay device dept	h limit: 206mm			
Front I/O	3 USB 2.0, 1 Headpho	ne Out, 1 Microphone In, and 1 IEEE 1394a			
Rear I/O	1 IEEE-1394a				
	6 USB 2.0				
	1 Serial				
	PS/2 keyboard and mo	use			
	2 RJ-45 to integrated G	Pigabit LAN			
	1 Audio Line In, 1 Audi	o Line Out, 1 Microphone In; audio ports can be retasked to function as line in,			
	line out, microphone, o	r headphone.			
Internal USB	3 USB 2.0 header				
Chassis Dimensions (H x W x D)	17.5 x 8.0 x 20.7 inche	es; 44.4 x 20.3 x 52.5 cm			
System Weight	Exact weights depend u	pon configuration			
,	Minimum config – 43 lk				
	Typical config – 46 lb (21 kg)			
	Maximum config – 64 l	b (29 kg)			
Temperature	Operating:	40° to 95° F (5° to 35° C)			
	Non-operating	-40° to 140° F (-40° to 60° C)			
Humidity	Operating:	8% to 85%			
,	Non-operating	8% to 90%			
Maximum Altitude (non-	Operating:	10,000 feet; 3,000 m			
pressurized)	Non-operating	30,000 feet; 9,100 m			
Power Supply	Choice of:	(00)000 1001/			
l ower supply	Choice of.				
	• 850W 85% (BRC	NZE) Efficient wide-ranging, active Power Factor Correction			
		VER) Efficient wide-ranging, active Power Factor Correction			
	· ·				
		wer supply can also supply 1250W of output power when the input voltage is			
		e input voltage is less than 105V, but greater than 90V for any reason, the			
maximum power that can be drawn is 1110W. An uninterruptible power supply (UPS) is highly					
	recommended if 1250V	V output power is desired.			



Overview

Interfaces Supported	 6-channel SATA 3.0 Gb/s Interface (6 Serial-ATA connectors on the motherboard, 4 channels are eSATA configurable for use with eSATA CTO/AMO Kit) 8-channel SAS interface (8 SAS connectors on the motherboard), SAS ports can be ported externally by using the SAS Bulkhead and/or Back Panel connector Kits 1 Floppy interface (1 Floppy connector), IEEE 1394a, USB 2.0
Hard Drive Controller	SATA and SAS controllers
Supported	



Supported Components

Processors		Factory	Option	Option Kit Part	Support
		Configured	Kit	Number	Notes
	Quad-Core Intel Xeon Processor 5500 Series with Intel®	64 Architectu	re		
	Intel Xeon X5570, 2.93GHz, 8MB cache, 1333MHz Memory, 6.4 GT/s QPI, 95W	Υ	Υ		
	Intel Xeon X5560, 2.80GHz, 8MB cache, 1333MHz Memory, 6.4 GT/s QPI, 95W	Υ	Υ		
	Intel Xeon X5550, 2.66GHz, 8MB cache, 1333MHz Memory, 6.4 GT/s QPI, 95W	Υ	Υ		
	Intel Xeon E5540, 2.53GHz, 8MB cache, 1066MHz Memory, 5.86 GT/s QPI, 80W	Υ	Υ		
	Intel Xeon E5530, 2.40GHz, 8MB cache, 1066MHz Memory, 5.86 GT/s QPI, 80W	Υ	Υ		
	Intel Xeon E5520, 2.26GHz, 8MB cache, 1066MHz Memory, 5.86 GT/s QPI, 80W	Υ	Υ		
	Intel Xeon E5506, 2.13GHz, 4MB cache, 800MHz Memory, 4.8 GT/s QPI, 80W	Υ	Υ		
	Intel Xeon E5504, 2.00GHz, 4MB cache, 800MHz Memory, 4.8 GT/s QPI, 80W	Υ	Υ		
	Quad-Core Intel Xeon Processor 5500 Series with Intel®	64 Architectu	re – High	Power	
	Intel Xeon W5580, 3.20GHz, 8MB L3, 1333MHz Memory 130W	', Y	Υ		

Sub-Section Description/Notes

Note 1: NCQ (Native Command Queuing) not supported in Red Hat Enterprise Linux

For hard drives, 1 GB = 1 billion bytes; TB = 1 trillion bytes. Actual formatted capacity is less. Up to 12 GB of hard drive (or system disk) is reserved for the system recovery software (XP and XP Pro). Up to 3 GB of system disk is reserved for system recovery software (Vista).

242	Нα	rd	Drives

Hard Drives		Option					
		Factory Configured	Option Kit	Kit Part Number	Support Notes		
	HP SAS (Serial Attached SCSI) Hard Drives for HP Works	tations					
	146 GB 15K rpm SAS 3.0 Gb/s 3.5" Hard Drive	Υ	Υ	EA330AA			
	300 GB 15K rpm SAS 3.0 Gb/s 3.5" Hard Drive	Υ	Υ	EM174AA			
	450 GB 15K rpm SAS 3.0 Gb/s 3.5" Hard Drive	Υ	Υ	FM803AA			
	Sub-Section Description/Notes						
	Up to 5 SATA drives, 5 SAS, drives, or 6 SATA 2.5", Small If 1st drive is SATA, 2nd drive can be EITHER SATA or SAS	•	SFF) drives	5			
Hard Drives	SATA (Serial ATA) Hard Drives for HP Workstations						
	160 GB 7,200 rpm SATA 3.0 Gb/s with NCQ 3.5" Hard Drive	Y	Υ	PV944A	See note 1		



SATA

O-4:--

Sunnorted	(amagante
SOPPORED	Components

250 GB 7,200 rpm SATA 3.0 Gb/s with NCQ 3.5" Hard Drive	Υ	Υ	EA788AA See note
320 GB 7,200 rpm SATA 3.0 Gb/s with NCQ 3.5" Hard Drive	Υ	Y	FH963AA
500 GB 7,200 rpm SATA 3.0 Gb/s with NCQ 3.5" Hard Drive	Υ	Y	PV943A See note
1 TB 7,200 rpm SATA 3.0 Gb/s with NCQ 3.5" Hard Drive	Υ	Y	GE262AA See note
160 GB 10K rpm SATA with NCQ 2.5" Hard Drive	Υ	Y	EW222AA See note
300 GB 10K rpm SATA with NCQ 2.5" Hard Drive	Υ	Υ	FM802AA
NOTE: 8 port SAS Controller included on the system board			

Hard Drive		Factory	.	Option Kit	•
Controllers		Configured	Option Ki	t Part Numbei	Support Notes
	Factory integrated RAID on motherboard for SATA of				
	RAID 0 Configuration - Striped Array	Υ	Υ		See note 1
	RAID 0 Data Configuration Boot/OS Drive + 2 Drive Striped Array	Y	Υ		See note 2
	RAID 1 Configuration - Mirrored Array	Υ	Υ		See note 3
	RAID 10 Configuration - Striped/Mirrored Array	Υ	Υ		
	RAID 5 Configuration - Parity Array	Υ	Υ		See note 3
	Integrated SATA 3.0 Gb/s Controller				
	Integrated SATA 3.0 Gb/s Controller, RAID 0, 1, 10, 5 supported	Υ	Υ		
	Integrated SAS controller With RAID 0, 1/1E				
	Integrated SAS controller With RAID 0 (IS), RAID 1(IM), RAID 10(IME) capability	Υ	Υ		
	HP SAS Back Panel Connector kit				
	HP SAS Back Panel Connector kit	Y	Y		Must have 4 or fewer SAS hard drives to configure this option
	HP SAS Back Panel Bulkhead Connector Kit				
	HP SAS Back Panel Bulkhead Connector Kit	Y	Y		HP SAS Back Panel Connector kit required. Internal SAS HD drives are not supported
	LSI MegaRAID® SAS 8888ELP Host Bus Adapter (H	BA)			
~/~°	LSI 8888ELP 8-port SAS HW RAID Card All RAID arrays must be less than 2 TB in size	Υ	Y	GE258AA	



Supported Components

NOTE 1: Minimum of 2 hard drives needed. All hard drives must be identical (size/speed/type/bus/functional capabilities). Must have 2, 3 or 4 HD Drives.

NOTE 2: Minimum of 3 SATA hard drives needed. All hard drives must be identical (size/speed/type/bus/functional capabilities).

At least 3 HD Drives required. May have 4th and 5th HD Drives. Drives must be the same drive (size/speed/type/functional capability).

NOTE 3: 2 SATA or 2 SAS hard drives required. All hard drives must be identical (size/speed/type/bus/functional capabilities).

NOTE 4: Minimum of 3 SATA hard drives needed. All SATA hard drives must be identical (size/speed/type/bus/functional capabilities). Must have 3 or 4 HD Drives. 5 HD Drives not allowed. SATA hardware RAID is not supported on Linux systems. The Linux kernel, with built-in software RAID, provides excellent functionality and performance. It is a good alternative to hardware-based RAID. Please visit http://h20000.www2.hp.com/bc/docs/support/SupportManual/c00060684/c00060684.pdf for RAID capabilities with Linux.

IS: Striping of 2 or more HDDs into a single logical volume

IM: Mirroring of 2 HDDs into a single logical volume

IME: Mirroring of 3 or more HDDs into a single logical volume

NOTE: Specific user-configured hardware SAS RAID configurations are supported on this Linux system.

Please visit: http://www.hp.com/support/linux hardware matrix for details

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported Multi Mixed
	Professional 2D					
	NVIDIA Quadro NVS 295 256MB Graphics Card					
	Entry 3D					
	ATI FirePro V3700 256MB PCle Graphics Card	Υ	Υ	FY944AA		1
	NVIDIA Quadro FX 380 256MB PCleGraphics Card	Υ	Υ	NB769AA		1
	NVIDIA Quadro FX 580 512MB PCle Graphics Card	Υ	Υ	FY945AA		1
	Mid-range 3D					
	NVIDIA Quadro FX 1800 768MB PCle Graphics Card	Υ	Υ	FY946AA		1
	ATI FirePro V5700 512MB PCle Graphics Card	Υ	Υ	FY947AA		1
	High End 3D					
	NVIDIA Quadro FX 3800 1.0GB PCIe Graphics Card (AVAILABLE JUNE 2009)	Υ	Υ	FY949AA		1
	NVIDIA Quadro FX 4800 1.5GB PCIe Graphics Card	Υ	Υ	FQ138AA		1
	NVIDIA Quadro CX - The Accelerator for Creative Suite 4	Υ	Υ			1
	NVIDIA Quadro FX 5800 4GB PCIe Graphics Card	Υ	Y	FZ559AA		1



1

QuickSpecs

Supported Components

ATI FirePro V7750 1.0GB PCle Graphics Y Y FY948AA Card

NOTE 1: This card consumes 2 PCle slots, reducing the maximum number of PCl cards in a system

Memory	СТО	Support Notes					
·	PC3-10600 DDR3-1333 ECC Registered DIMMs CTO						
	24GB (6x4GB) DDR3-1333 ECC Registered RAM 2-CPU	2 Processors Required					
	32GB (8x4GB) DDR3-1333 ECC Registered RAM 2-CPU	2 Processors Required					
	48GB (12x4GB) DDR3-1333 ECC Registered RAM 2-CPU	2 Processors Required					
	96GB (12x8GB) DDR3-1333 ECC Registered RAM 2-CPU	2 Processors Required					
	64GB (8x4GB+4x8GB) DDR3-1333 ECC Registered RAM 2-CPU	2 Processors Required					
	PC3-10600 DDR3-1333 ECC Unbuffered DIMMs CTO						
	1GB (1x1GB) DDR3-1333 ECC Unbuffered RAM 1-CPU	1 Processor Configuration					
	2GB (2x1GB) DDR3-1333 ECC Unbuffered RAM 1-CPU	1 Processor Configuration					
	3GB (3x1GB) DDR3-1333 ECC Unbuffered RAM 1-CPU	1 Processor Configuration					
	2GB (2x1GB) DDR3-1333 ECC Unbuffered RAM 2-CPU	2 Processors Required					
	After Market Options (AMO)						
	PC3-10600 DDR3-1333 ECC Registered DIMMs AMO						
	4GB (1x4GB) DDR3-1333 ECC Registered RAM						
	8GB (1x8GB) DDR3-1333 ECC Registered RAM	8GB (1x8GB) DDR3-1333 ECC Registered RAM					
	PC3-10600 DDR3-1333 ECC Unbuffered DIMMs AMO	PC3-10600 DDR3-1333 ECC Unbuffered DIMMs AMO					
	1GB (1x1GB) DDR3-1333 ECC Unbuffered RAM						
	2GB (1x2GB) DDR3-1333 ECC Unbuffered RAM	2GB (1x2GB) DDR3-1333 ECC Unbuffered RAM					
	NOTE: You cannot intermix registered and unbuffered DIMMs. The sys	stem will not work.					

Multimedia and Audio Devices		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Integrated Intel/Realtek HD ALC262 Audio	Υ	Ν		
	HP Thin USB Powered Speakers	Υ	Υ	KK912AA	
	Creative X-Fi Titanium PCle Audio Card	Υ	Υ	NH222AA	



Supported Components

Optical and Removable Storage		Factory	Option	Option Kit Part	
- 3		Configured	Kit	Number	Support Notes
	HP DVD-ROM Drive	Υ	Υ	AR629AA	See note 2
	HP DVD+/-RW Drive	Υ	Υ	EW269AA	See note 3
	HP Slot Load DVD+/-RW Drive	Υ	Ν		See note 1
	HP Blu-Ray Writer	Y	Y	AR482AA	Available May 2009
	HP 22-in-1 Media Card Reader Kit (Workstations)	Ν	Υ	NK361AA	
	HP DX115 Removable Drive Enclosure				
	HP DX115 Carrier with 160GB SATA HDD	Υ	Υ	FZ577AA	
	HP DX115 Removable HDD Frame/Carrier	Ν	Υ	FX576AA	
	HP DX115 Removable HDD Carrier	Ν	Υ	NB792AA	

Actual speeds may vary. Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. As Blu-Ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-Ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

NOTE 1: May only order one. NOTE 2: Cannot be 2nd drive.

NOTE 3: LightScribe, is supported on Windows ONLY and creates a grayscale image similar to black and white photography. LightScribe media required and sold separately. Double-layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Controller Cards		Factory Configured		Option Kit Part Number	Support Notes
	HP IEEE 1394b FireWire PCle Card	Υ	Υ	NK653AA	

Supported Components

Monitors	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP LP1965 19-inch LCD Monitor	Y	Υ	RA373A	
HP LP2275w 22-inch Widescreen LCD	Monitor Y	Υ	KE289A	
HP LP2475w 24-inch Widescreen LCD	Monitor Y	Υ	KD911A	
HP DreamColor LP2480zx Professional	Display Y	Υ	GV546A	
HP LP3065 30-inch Widescreen LCD M	onitor Y	Υ	EZ320A	
NOTE: Supported by all Operating Syst	ems available from HP (screen siz	ze diagono	ılly measure	d)

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Integrated Broadcom 5764 PCle LOM Controller	Υ	Ν		
	Broadcom NetXtreme Gigabit Ethernet Plus NIC (PCle)	Υ	Υ	FS215AA	
	HP NC360T PCI Express Dual Port Gigabit NIC	Ν	Υ	KU004AA	
	Intel Gigabit CT Desktop NIC	Ν	Υ	FH969AA	
	"Gigabit" Ethernet indicates compliance with IEEE standard		•		

Ethernet server and network infrastructure is required.

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Security Cable with Kensington Lock	Ν	Υ	PC766A	
	HP Chassis Intrusion Sensor	Υ	Ν		
	HP Z6/Z8 Adjustable Sliding Rail Rack Kit	Ν	Υ	NN124AA	

Input Devices		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP PS/2 Standard Keyboard	Υ	Υ	DT527A	
	HP USB Standard Keyboard	Υ	Υ	DT528A	
	HP PS/2 Optical Scroll Mouse	Υ	Υ	EY703AA	
	HP USB 2-Button Optical Scroll Mouse	Υ	Υ	DC172B	
	HP USB Laser Mouse	Υ	Υ	GW405AA	
	HP USB Optical 3-Button Mouse	Υ	Υ	DY651A	
	HP USB Smart Card Keyboard	Ν	Υ	ED707AA	
	HP 2.4GHz Wireless Keyboard & Mouse	Ν	Υ	NB896AA	
	HP USB Optical 3-Button 2.9M OEM Mouse	Ν	Υ	ET424AA	
	HP SpaceExplorer 3D USB Controller	Ν	Υ	RY429AA	
	HP SpacePilot 3D USB Intelligent Controller	Ν	Υ	EF390AA	



Supported Components

Other Hardware	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Internal USB Port Kit	Υ	Υ	EM165AA	
HP SAS Back Panel Connector	Υ	Υ	EM164AA	
HP eSATA PCI Cable Kit	Υ	Υ		
HP Power Cord Kit	Υ	Υ		
HP ENERGY STAR 5.0 Enabled Configuration	Υ	Υ		

Software		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Performance Tuning Framework	Υ	Ν		
	Roxio Easy Media Creator (CD or DVD burner)	Υ	Ν		
	Intervideo WinDVD with DVD player	Υ	Ν		
	HP Backup and Recovery	Y	Ν		Supported on Windows XP ONLY
	PDF Complete	Υ	Ν		
	Microsoft Office 2007 Small Business Edition	Υ	Ν		
	Microsoft Office 2007 Trial Edition	Υ	Ν		
	HP Client Manager Software v6.2 (optional download)	Y	Ν		
	HP ProtectTools Security	Y	N		Must select as a Configure to Order Option. Delivered as a "Drop in the Box" CD

Supported Components

Operating Systems

Support Notes

Genuine Windows Vista® Business 32-bit

Certain Windows Vista product features require advanced or additional hardware. See

www.microsoft.com/windowsvista/getready/hardwarereqs.mspx and www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit www.windowsvista.com/upgradeadvisor.

Genuine Windows Vista® Business 64-bit

Certain Windows Vista product features require advanced or additional hardware. See

www.microsoft.com/windowsvista/getready/hardwarereqs.mspx and www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit www.windowsvista.com/upgradeadvisor.

Genuine Windows Vista® Business 32-bit with downgrade to Windows® XP Professional 32-bit custom installed

Windows Vista Business disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order at least 25 customer systems with the same custom image.

Genuine Windows Vista® Business 64-bit with downgrade to Windows® XP Professional x64 custom installed Windows Vista Business disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order at least 25 customer systems with the same custom image.

HP Linux Installer Kit

see: http://www.hp.com/workstations/software/linux



System Board					
System Board Form Factor	Custom Form Factor, 13" x 14.25"				
Processor Socket	Dual LGA 1366				
CPU Bus Speed	QPI: Up to 6.4GT/sec				
Chipset	Intel® 5520				
Super I/O Controller	SMSC SCH5327, Rev B				
Memory Expansion Slots	slots (6 slots per CPU)				
Memory Type Supported	DDR3, RDIMM (Registered) or UDIMM (Unbuffered), ECC				
Memory Modes	NUMA (Non-Uniform Memory Architecture), Memory Node Interleave				
Memory Speed Supported	800MHz, 1066MHz, & 1333MHz				
Memory					
Maximum Memory	Supports up to 24GB using UDIMMs Supports up to 192GB using RDIMMs Single Processor Memory Loading				
	Single Processor – CPU0				
	Capacity DIMM1 DIMM2 DIMM3 DIMM4 DIMM5 DIMM6				
	1 GB 1 GB 1 GB 1 GB				
	3GB 1GB 1GB 1GB				
	4GB 2GB 2GB 2GB 2GB				
	8GB 2GB 2GB 2GB 2GB				
	12GB 2GB 2GB 2GB 2GB 2GB				
	Dual Processor Memory Loading				
	Dual Processor				
	CPU0 CPU1 Capacity DIMM1 DIMM2 DIMM3 DIMM4 DIMM5 DIMM6 DIMM1 DIMM2 DIMM3 DIMM6				
	2GB 1GB 1GB 1GB 1GB 1GB				
	6GB 1G5				
	12GB 2GB 2GB 2GB 2GB 2GB 2GB 2GB 2GB 2GB				
	24G8 4G8 4G8 4G8 4G8 4G8 4G8 4G8 4G8 4G8				
	48G8 4G5 4G5 4G5 AG5 AG5 AG5 AG5 AG5 AG5 AG5 AG5 AG5 A				
	94G8 8G8 8G8 8G8 8G8 8G8 8G8 8G8 8G8 8G8				
	144GB 16GB 8GB 16GB				
	192GB 16G5				
Memory Configuration	Not all memory configurations possible are represented below. Also, 512 MB configurations are				
(Supported)	not supported for 64-Bit operating systems.				
	Only ECC DIMMs are supported.				
	RDIMM and UDIMM memory modules cannot be mixed in the system.				
	Do not install memory modules into memory slots if corresponding processor is not installed.				
	 Dual processor configurations with memory modules installed for only one processor is not supported. 				
	 The 4GB DIMM for Z4 and Z6 is not compatible with the Z8 4GB DIMM. They are not 				
	interchangeable.				



system rechnical spe	Ciliculions			
PCI Express Connectors (Gen2 Rev 0.7 connectors)	PCle2 x16, qty 2 PCle2 x16 (8), qty 2 PCle2 x8 (4), qty 1 PCle x8 (4), qty 1			
PCI Connectors (5.0V)		Cl 32b, 33MHz (supports 64-bit cards), qty 1		
Interfaces Supported	Integrated 6-channel SATA 3.0Gb/sec controller with RAID 0, 1, 5, 10 and NCQ. (Factory integrated RAID is Microsoft Windows only)			
Serial Attached SCSI	Integrated 8-channel SAS 3.0Gb/sec cor	ntroller with HW RAID 0, 1,10.		
Integrated RAID	SATA: RAID 0, 1, 5, 10AS: HW RAID 0, 1, 10			
Integrated Graphics	None			
Network Controller	Dual Controller Broadcom 5764 PCI-E LAN Controller Memory Integrated 48KB receive buffer and 8KB transmit buffer Data rates supported 10/100/1000 Mbps Compliance IEEE 802.3, 802.3AB and 802.3u compliant, 802.3x flow control Bus architecture PCIe 1.0a Data path width X1 to each controller Data path speed 2.5Gbit per sec per direction transfer rate Data transfer mode Bus-master DMA Power requirement 1.0 watts @ +3.3V AUX supply Boot ROM support Yes Network transfer rate 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-TX (full-duplex) 2000 Mbps Microsoft Windows Vista Business 32 and 64, Microsoft Windows XP			
PCI-X Connectors	Management capabilities WOL, PXE 2.1 None			
PCI Card Guide	Yes			
Wake on LAN	Yes			
Integrated Trusted Platform Module	TPM 1.2			
ASF 1.0 & 2.0 (Alert Standard Format)	Yes			
SATA Connectors	6 ports/connectors (Included are 4 eSATA kit)	A configurable with optional eSATA After-Market Option cable		
IEEE 1394 Connector(s)	Front	Yes, 1394a		
	Rear	Yes, 1394a		
	Internal	None		
USB Connector(s)	Front	Yes, qty 3		
	Rear	Yes, qty 6		
	Internal Yes, qty 3			
HD Integrated Audio	Yes			
Flash ROM	Yes, SPI Rom			



System reclinical Spe	cinculoris
Clear Fan Header	No
CPU Fan Header	Yes, qty 2
Chasiss Fan Header	Yes, a single fan header for 2 fans.
Front PCI Fan Header	Yes, qty 2
Front Control Panel/Speaker Header	Yes
CMOS Battery Holder - Lithium	Yes
Integrated Trusted Platform Module	Integrated TPM 1.2
Power Supply Headers	Yes: 9x2, 5x2, 4x2
Power Switch, Power LED & Hard Drive LED Header	Yes
Clear Password Jumper	Yes
Serial Port	Yes, on rear panel
Parallel Port	No
Keyboard/Mouse	Yes
Power Supply	850W 85% Efficient Wide-Ranging, Active PFC, Custom 1110W 89% Efficient Wide-Ranging, Active PFC, Custom NOTE: The 1110W power supply can also supply 1250W of output power when the input voltage is greater than 105V. If the input voltage is less than 105V, but greater than 90V for any reason, the maximum power that can be drawn is 1110W. An uninterruptible power supply (UPS) is highly recommended if 1250W output power is desired.
Operating Voltage Range	90-269 VAC
Rated Voltage Range	100-240 VAC 118 VAC
Rated Line Frequency	50-60 Hz 400 Hz
Operating Line Frequency Range	47-66 Hz 393 - 407 Hz
Rated Input Current	850W: 11A @ 100-127V, 5.5A @ 200-240V, 11A @ 118V 1110W: 12A @ 100V 1250W: 12A @ 115V, 10A @ 200-240V, 12A @ 118V
Heat Dissipation	850W: Typical = TBD, Max = TBD 1110W: Typical = TBD, Max = TBD
Power Supply Fan	850W: 2x80x25 mm variable speed 1110W: 2x80x25 mm variable speed
ENERGY STAR® qualified (Config Dependent)	Yes
80 PLUS Compliant	850W 85% BRONZE 1110W 89% SILVER
FEMP Standby Power Compliant 115V (Wake- on LAN disabled) (<2W in S5 - Power Off)	Yes



Power consumption in sleep mode (as defined by ENERGY STAR) - Suspend to RAM (S3)	850W: <20W 1110W: <20W				
Built-in Self Test (BIST) LED	Yes				
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes				
ENERGY STAR® qualified	Yes				
AUX IN (audio)	No				
Clear CMOS Button	Yes				
Chassis Speaker Header	Yes, as part of Front UI (C	Control Panel) cable heade	r		
Multibay Header	No				
Integrated Gigabit Ethernet	Yes, dual port.				
Access Panel Solenoid Lock Header	Yes				
Access Panel Intrusion Sensor Header	Yes, as part of Front UI (Control Panel) cable header				
Memory Fan Connector	Yes, blind-mate				
Z800 Required Power Sup	ply Info				
Power Supply	850WCustom PSU - (W	ide Ranging Active PFC)		om PSU - (Wide Ranging e PFC)	
Operating Voltage Range	90 - 26	69 VAC	90 - 20	69 VAC	
Rated Voltage Range	100 - 240 VAC	118 VAC	100 - 240 VAC	118 VAC	
Rated Line Frequency	50-60 Hz	400 Hz	50-60 Hz	400 Hz	
Operating Line Frequency Range	47 - 66 Hz	393 - 407 Hz	47 - 66 Hz	393 - 407 Hz	
Rated Input Current	11.0A @ 110-127 VAC 5.5A @ 200-240 VAC	11.0A @118 VAC	12A @ 100 VAC, 1110 W 12A @ 115 VAC, 1250 W 10A @ 200-240 VAC, 1250 W	12A @118 VAC, 1250W	
Heat Dissipation (Configuration and software dependent)	Typical 1707 btu/ Max 3558 btu/hi	r (892 kg-cal/hr)	Max1 4457 btu/h	/hr (536 kg-cal/hr) nr (1123 kg-cal/hr) nr (1265 kg-cal/hr)	
Power Supply Fan	2x80x25 mm v	variable speed	2x80x25 mm	variable speed	
Energy Star Compliant (config dependent)	YE	ES	Y	ES	
80 PLUS® Compliant	Yes, B	ronze	Yes,	Silver	



FEMP Standby Power Compliant@115V (Wake-on LAN disabled)(<2W in S5- Power Off)	YES	YES
EuP Compliant@230V (<1 W in S5-Power Off)	YES	YES
Power Consumption in sleep mode (as defined by ENERGY STAR) - Suspend to RAM (S3) (Instantly Available PC) measured at 115V.	<20W	<20W
Built-in Selft Test LED	YES	YES
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V	YES	YES
	*Input Voltage Restrictions	

System Configuration						
Example Configuration	Processor Info	1xXeon E5504 (2.00GHZ, 4MB/800)				
#1	Memory Info	3x1GB DR 1067 MHz (UDIMM)				
	Graphics Info	1xFX1800				
	Disks/Optical/Floppy	1x250GB SATA / 1 Optical / 1 Floppy				
	PSU	850W 80 PLUS® BRONZE				

Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	130.5 W		127.4 W		130.5 W	
Windows Busy Typ (S0)	205.32 W		201.97 W		208.41 W	
Windows Busy Max (S0)	240.84		235.49 W		245.00 W	
Sleep (S3)	6.39 W	6.02 W	6.82 W	6.43 W	6.37 W	5.98 W
Off (\$5)	1.43 W	1.20 W	1.85 W	1.65 W	1.39 W	1.17 W
Zero Power Mode (EuP)	0.40 W		0.85 W		0.37 W	

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	445.4 btu/hr		445.4 btu/hr		445.4 btu/hr	
Windows Busy Typ (S0)	700.76 btu/hr		689.32 btu/hr		711.3 btu/hr	
Windows Busy Max (S0)	821.99	9 btu/hr	803.73 btu/hr		836.19 btu/hr	
Sleep (S3)	21.8 btu/hr	20.6 btu/hr	23.3 btu/hr	21.9 btu/hr	21.7 btu/hr	20.4 btu/hr
Off (\$5)	4.88 btu/hr	4.10 btu/hr	6.31 btu/hr	5.63 btu/hr	4.74 btu/hr	3.99 btu/hr
Zero Power Mode (EuP)	1.37 btu/hr		2.90 btu/hr		1.26 btu/hr	

Example Configuration	Processor Info	2xXeon E5570 (2.93GHZ, 8MB/1333)
#2	Memory Info	6x1GB DR 1333 MHz (UDIMM)
	Graphics Info	1xFX3800
Disks/Optical/Floppy 2x		2x250GB SATA / 2 Optical / 1 Floppy
	PSU	850W 80 PLUS® BRONZE

Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	199.10 W		196.20 W		198.20 W	
Windows Busy Typ (S0)	445.20 W		434.90 W		443.40 W	
Windows Busy Max (S0)	516.50 W		504.00 W		524.60 W	
Sleep (S3)	7.84 W	7.49 W	8.29 W	7.89 W	7.92 W	7.47 W
Off (S5)	1.43 W	1.21 W	1.86 W	1.64 W	1.39 W	1.18 W
Zero Power Mode (EuP)	0.41 W		0.84 W		0.38 W	

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	679.53 btu/hr		669.63 btu/hr		676.46 btu/hr	
Windows Busy Typ (S0)	1519.47 btu/hr		1484.31 btu/hr		1513.32 btu/hr	
Windows Busy Max (S0)	1762.81 btu/hr		1720.15 btu/hr		1790.46 btu/hr	
Sleep (S3)	26.8 btu/hr	25.6 btu/hr	28.3 btu/hr	26.9 btu/hr	27.1 btu/hr	25.5 btu/hr
Off (\$5)	4.88 btu/hr	4.13 btu/hr	6.35 btu/hr	5.60 btu/hr	4.74 btu/hr	4.03 btu/hr
Zero Power Mode (EuP)	1.40 btu/hr		2.87 btu/hr		1.30 btu/hr	

Example Configuration	Processor Info	2xW5580 (3.2GHZ, 8MB/1333)
#3	Memory Info	6x4GB DR 1333 MHz (RDIMM)
	Graphics Info	1xFX4800
	Disks/Optical/Floppy	2x300GB 15k SAS / 2 Optical / 1 Floppy
	PSU	1110W 80 PLUS® SILVER



Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	259.5 W		253.10 W		260.10 W	
Windows Busy Typ (S0)	624.90 W		615.60 W		638.70 W	
Windows Busy Max (S0)	738.10 W		732.40 W		749.70 W	
Sleep (S3)	12.53 W	11.58 W	12.59 W	11.63 W	12.56 W	11.56 W
Off (S5)	2.12 W	1.32 W	2.56 W	1.73 W	2.10 W	1.30 W
Zero Power Mode (EuP)	0.46 W		0.87 W		0.43 W	

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	885.67 btu/hr		896.83 btu/hr		887.72 btu/hr	
Windows Busy Typ (S0)	2132.78 btu/hr		2101.04 btu/hr		2179.88 btu/hr	
Windows Busy Max (S0)	2519.14 btu/hr		2499.68 btu/hr		2558.73 btu/hr	
Sleep (S3)	42.8 btu/hr	39.5 btu/hr	42.9 btu/hr	39.7 btu/hr	42.9 btu/hr	39.5 btu/hr
Off (S5)	7.24 btu/hr	4.51 btu/hr	8.74 btu/hr	5.90 btu/hr	7.15 btu/hr	4.44 btu/hr
Zero Power Mode (EuP)	1.40 btu/hr		2.87 btu/hr		1.30 btu/hr	

Example Configuration	Processor Info	2xW5580 (3.2GHZ, 8MB/1333)
#4	Memory Info	8x4GB DR 1333 MHz (RDIMM)
	Graphics Info	2xFX5800
	Disks/Optical/Floppy 4x300GB 15k SAS / 2 Optical / 1 Flopp	
	PSU	1110W 80 PLUS® SILVER

Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	436.40 W		426.60 W		433.60 W	
Windows Busy Typ (S0)	845.60 W		811.90 W		855.30 W	
Windows Busy Max (S0)	970.30 W		966.30 W		994.50 W	
Sleep (S3)	13.82 W	12.70 W	14.00 W	13.06 W	13.88 W	12.75 W
Off (S5)	2.12 W	1.33 W	2.54 W	1.73 W	2.10 W	1.30 W
Zero Power Mode (EuP)	0.46 W		0.86 W		0.43 W	

System Technical Specifications

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows Idle (S0)	1489.43 btu/hr		1455.99 btu/hr		1479.88 btu/hr	
Windows Busy Typ (S0)	2886.03 btu/hr		2771.01 btu/hr		2919.14 btu/hr	
Windows Busy Max (S0)	3311.63 btu/hr		3297.9	8 btu/hr	3394.2	3 btu/hr
Sleep (S3)	47.2 btu/hr	43.4 btu/hr	47.8 btu/hr	44.6 btu/hr	47.4 btu/hr	43.5 btu/hr
Off (\$5)	7.24 btu/hr	4.54 btu/hr	8.67 btu/hr	5.90 btu/hr	7.65 btu/hr	4.44 btu/hr
Zero Power Mode (EuP)	1.40 btu/hr		2.87	btu/hr	1.30	btu/hr

, ,	Processor Info	2xIntel Xeon W5580 (3.2GHZ, 8MB/1333)
#5	Memory Info	8x2GB DR 1333 MHz (UDIMM)
	Graphics Info	1xFX5800
	Disks/Optical/Floppy	2x1000GB SATA / 1 Optical / 1 Floppy
	PSU	1110W 80 PLUS® SILVER

Energy Consumption	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
On-Idle (ENERGY STAR* Idle (S0))	174.0 W		169.9 W		172.1 W	
ENERGY STAR = PMAX Windows running Unneck and Viewperf	569.4 W		556.7 W		570.	.1 W
ENERGY STAR "Sleep" (S3)	9.4 W	-	9.8 W	-	9.7 W	_
ENEGY STAR "Standby" (Off) (S5)	2.1W	_	2.6 W	_	2.2 W	-

Heat Dissipation**	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
On-Idle (ENERGY STAR* Idle (S0))	593.9	btu/hr	579.9	btu/hr	587.4	btu/hr
ENERGY STAR = PMAX Windows running Unneck and Viewperf	1943.4 btu/hr		1900.0 btu/hr		1945.8	3 btu/hr
ENERGY STAR "Sleep" (S3)	32.1 btu/hr	-	33.4 btu/hr	-	33.1 btu/hr	-
ENEGY STAR "Standby" (Off) (S5)	7.2 btu/hr	_	8.9btu/hr	_	7.5 btu/hr	_

NOTES:

This product is in compliance with US executive order 13221, WOL (wake on LAN) disabled.



^{*}Energy Star low energy mode

^{**} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (Entry-level and High-end configurations)			
System Configuration	Processor Info	Dual Intel Xeon X5570 quad-core 2.93 GHz	
(Entry level)	Memory Info	4 x 1GB DDR3 1333 MHz	
	Graphics Info	Single nVidia NVS 290	
	Disks/Optical/Floppy	2 x 250 GB 7200 RPM SATA/ CD/DVD-ROM/ TEAC 3.5" Floppy	

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure
7779 and ISO 9296)	Idle	3.9	21
	SATA Hard drive Operating (random reads)	3.9	22
	Floppy Drive Operating (continuous copy)	Not Tested	Not Tested
	DVD-ROM Operating (sequential reads)	5.0	36

-1 - 3	Processor Info	Dual Intel Xeon W5580 quad-core 3.2 GHz
(High-end)	Memory Info	4 x 1GB DDR3 1333 MHz
	Graphics Info Single nVidia FX 4800	
	Disks/Optical/Floppy	2 x 450 GB 15K SAS/ CD/DVD-ROM/ TEAC 3.5" Floppy

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure
7779 and ISO 9296)	Idle	4.6	28
	SATA Hard drive Operating (random reads)	4.9	
	Floppy Drive Operating (continuous copy)	Not Tested	
	DVD-ROM Operating (sequential reads)	5.1	

Environmental Requirements	Temperature	Operating: 40° to 95° F (5° to 35° C) Non-operating: -40° to 140° F (-40° to 60° C)
	Humidity	Operating: 8% to 85% RH, non-condensing Non-operating: 8% to 90% RH, non-condensing
	Maximum Altitude	Operating: 10,000 feet (3,000 m) Non-operating: 30,000 feet (9,100 m)
	Dynamic (new)	Shock Operating: ½-sine: 40g, 2-3ms Non-operating: ½-sine: 160 cm/s, 2-3ms (~100g) square: 422 cm/s, 20g NOTE: Values represent individual shock events and do not indicate repetitive shock events. Vibration Operating random: 0.5g (rms), 5-300 Hz Non-operating random: 2.0g (rms), 10-500 Hz NOTE: Values do not indicate continuous vibration.
	Cooling	Above 5000 ft (1524 m) altitude, maximum operating temperature is derated by 1.8° F (1° C) per 1000 ft (305 m) elevation increase

Physical Security and	d Serviceability
Access Panel	Tool-less Includes system board and memory information
Optical Drive	Tool-less, no carrier or rails required
Floppy Drive	Tool-less
Hard Drives	Tool-less
Expansion Cards	Tool-less
Processor Socket	Tool-less
Green User Touch Points	Yes, on tool-free internal chassis components
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Tool-less, retained by Front PCI Card Guide
Dual Color Power and HD LED on Front of Computer	Yes
Configuration Record SW	Yes
Over-Temp Warning on Screen	Yes
Restore CD Set	Restores the computer to its original factory shipping image - Can be obtained via HP Support
Dual Function Front Power Switch	Yes, causes a fail-safe power off when held for 4 seconds
Padlock Support	No



Cable Lock Support	Yes, Kensington Cable Lock (optional): Prevents entire system theft only. 3mm x 7mm slot at rear a system		
Universal Chassis Clamp Lock Support	No		
Solenoid Lock and Hood Sensor	No		
Rear Port Control Cover	Yes, locks rear IO cables to prevent cable theft		
Serial, Parallel, USB, Audio, Network, Enable/Disable Port Control	Yes		
Removable Media Write/Boot Control	Yes, prevents ability to boot from removable media on supported devices (and can disable writes to media)		
Power-On Password	Yes, prevents an unauthorized person from booting up the workstation		
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration		
3.3V Aux Power LED on System PCA	No		
NIC LEDs (integrated) (Green & Amber)	Yes		
CPUs and Heatsinks	A torx driver (T15) is needed to remove the CPU heatsink(s) before the CPU can be removed. CPU removal is tool-less		
Power supply diagnostic LED	Yes		
Power Button	Yes		
Power LED	Yes, blue (normal), red (fault)		
Hard drive activity LED	Yes, green		
Internal speaker	Yes		
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.		
OS CD (Restore OS CD)	Restores computer to its original factory shipping Operating System - No recovery CDs will ship with Windows XP, Vista or Linux - an ISO image will be available on an HD partition.		
ASF 2.0 support (Alert Standard Format)	Industry-standard specification for network alerting in operating system-absent environments		
Cooling Solutions	Air cooled forced convection, liquid cooling (optional)		
Power Supply Fans	2x - 80mm x 25mm		
CPU Heatsink Fan(s)	Mainstream (<=95W): 80mm x 15mm Performance (>95W): 92mm x 15mm		
Chassis Fans	Rear: 2x - 92mm x 25mm Front (850W config): 1x - 92mm x 25mm (upper position) Front (1110W config): 2x - 92mm x 25mm		
Memory Fans	2x - 80mm x 25mm		
Insight Diagnostics	 HP Insight Diagnostics Offline Edition The diagnostics utility enables you to perform testing and to view critical computer hardware and software configuration information from various sources. This utility enables you to: Run diagnostics 		



System rechined spe	
	iew the hardware configuration of the system
	Key features and benefits HP Insight Diagnostics simplifies the process of effectively identifying, diagnosing, and isolating the hardware issues. In addition to robust management tools, service tools can be invaluable in quickly resolving system problems. To streamline the service process and resolve problems quickly, it is necessary to have the right information available at the time that a service call is placed. The primary information requirement, which is also the one that provides the greatest insight into potential system issues, is the configuration of the system. Insight Diagnostics helps provide higher system availability. Typical uses of the Insight Diagnostics are:
	 Testing and diagnosing apparent hardware failures Documenting system configurations for upgrade planning, standardization, inventory tracking, disaster recovery, and maintenance Sending configuration information to another location for more in-depth analysis
Access Panel Key Lock	Yes, prevents removal of the access panel and all internal components including optical and floppy drives
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).
	 Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system
Trusted Platform Module Chip with optional ProtectTools Software	Yes
Integrated Chassis Handles	Yes
Power Supply	Tool-less, direct-connect (blind-mate)
PCI Card Retention	Yes, rear (all), middle (full-height cards), front (full-length with extender cards)
Flash ROM	Yes. SPI ROM
Diagnostic Power Switch LED on board	Yes
Clear Password Jumper	Yes
Clear CMOS Button	Yes
CMOS Battery Holder for easy Replacement	Yes
DIMM Connectors for easy Upgrade	Yes
HP ProtectTools Security Manager	Yes - not supported on Microsoft XP x64 or Linux

BIOS	
BIOS 32-bit Services	Standard BIOS 32-Bit Service Directory Proposal v0.4.
PCI 3.0 Support	Full BIOS support for PCI Express through industry standard interfaces.
ATAPI	ATAPI Removable Media Device BIOS Specification Version 1.0.
BBS	BIOS Boot Specification v1.01



/ \/\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	W/M is Missassitis implementation of Wah Broad Estaration Management (M/BEM) for Windows W/M is
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system settings controlled by the BIOS.
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.
Replicated Setup	Saves BIOS settings to diskette or USB flash drive in human readable file. Repset.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 setup).
SMBIOS	System Management BIOS 2.6, for system management information
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	Monitors the temperature state within the chassis. Three modes:
	 NORMAL - normal temperature ranges ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced Configuration and Power Management Interface)	 Allows the system to enter and wake from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 2.0 for full compatibility with 64-Bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
ASF 2.0 Compliant	Allows workstation status to be monitored on a remote console.
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS) so that management SW applications can use and report this information.
System board revision level	 Allows management SW to read the revision level of the system board Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.es



Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard.
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 12 languages with local keyboard mappings.
Asset Tag	Allows the user or MIS to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.
Adaptive Cooling	Fan control parameters are set according to detected hardware configuration for optimal acoustics.
Pre-boot Diagnostics	Early (pre-video) critical errors are reported via beeps and blinks on the power LED.
Industry Standard Specification Support	
Industry Standard	Revision Supported by the BIOS
ACPI	Advanced Configuration and Power Management Interface, Version 2.0c
ASF	Alert Standard Format Specification, Version 2.0
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0
EDD	 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI	 PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7
PCI Express	PCI Express Base Specification, Revision 2.0
PMM	POST Memory Manager Specification, Version 1.01
SATA	 Serial ATA Specification, Revision 1.0a Serial ATA 3.0Gb/s: Extensions to Serial ATA 1.5Gb/s, Revision 1.0
SPD	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B
TPM	Trusted Computing Group TPM Specification Version 1.2
UHCI	Universal Host Controller Interface Design Guide, Revision 1.1
USB 1.1	Universal Serial Bus Revision 1.1 Specification
USB 2.0	Universal Serial Bus Revision 2.0 Specification
SMBIOS	System Management BIOS Reference Specification, Version 2.6

System Software Management and Updating	
HP Client Management	Visit: http://www.hp.com/go/easydeploy
Solutions	
Product Change	 Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile. PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition. Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.
Support Software CD & WWW	Yes



HP Client Manager	Visit: http://www.hp.com/go/easydeploy
System Software Manager	Visit: http://www.hp.com/go/ssm
(free)	
Social and Environmental	
Responsibility	
Eco-Label Certifications &	This product has received or is in the process of being certified to the following approvals and may be
Declarations	labeled with one or more of these marks:
	ENERGY CTAR LEG L. L. L. L. C. C. C. C. L. L. L.
	ENERGY STAR qualified selectable configurations (Not in Linux) US Fordered Forgers (Africa) (FEAAD)
	 US Federal Energy Management Program (FEMP) China Energy Conservation Program
	IT ECO declaration
	Japan PC Green label*
	Superior Sup
	*This product conforms to the examination standards (2003 version) under JEITA's 'PC Green Label
	System.'
Recycled Content and	• This product is >90% recycle-able when properly disposed of at end of life.
Design for Recycling	 Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and
	ISO1043.
	This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE)
	Directive - 2002/96/EC.
Batteries	This product complies with ISO standards:
	EU Directive 91/157/ EEC
	• EU Directive 93/ 86/ EEC
	EU Directive 98/ 101/ EEC
	Batteries used in the product do not contain:
	Mercury greater than 5ppm by weight
	Cadmium greater than 10ppm by weight
	Lead greater than 4000ppm by weight
	Battery size: CR2032 (coin cell)
	Battery type: Lithium
Restricted Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the
	HP General Specification for the Environment at
	http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
	 Asbestos
	Batteries - Mercury
	Batteries - Cadmium
	Batteries - Lead (non-rechargeable)
	Batteries - Non-rechargeable Alkaline and Carbon-Zinc Batteries
	Batteries - Classification as "Not Restricted" for Transport
	Brominated Flame Retardants (PBBs, PBDEs, including DecaBDE)
	Brominated Flame Retardants (all BFRs in external case plastic parts)
	Cadmium and its compounds Cartain And Calamate
	Certain Azo Colorants Chloringtod Hydrogerbans
	Chlorinated HydrocarbonsChlorinated Paraffins
	Chlorinated Farattins Formaldehyde
~!~°	1 o i omidiacityde



System Technical Spe	ecitications
	 Formaldehyde - emissions Hexavalent Chromium and its compounds in metallic applications Hexavalent Chromium and its compounds in non-metallic applications Lead and its compounds Lead in paint Lead in Polyvinyl Chloride (PVC) coating of external cables, wires and cords Mercury and its compounds Nickel on external surfaces Ozone Depleting Substances (ODS) Polycyclic Aromatic Hydrocarbons (PAH) Perfluorooctane sulfonates (PFOS) in parts Perfluorooctane sulfonates (PFOS) in preparations Polychlorinated Biphenyls (PCBs) and Polychlorinated Terphenyls (PCTs) Polychlorinated Naphthalenes Polyvinyl Chloride (PVC) in external case plastic parts Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging	HP Workstation product packaging meets the following (refer to the HP General Specification for the
rackaging	Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html:
	Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment (see link above).
	Does not contain ozone-depleting substances (ODS).
	Design packaging materials for ease of disassembly.
	Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed.
	Maximizes the use of post-consumer recycled content materials in packaging materials.
	All packaging material is recyclable.
	 Reduces size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
Longevity and Upgrading	 This product is designed to be upgraded, possibly extending its useful life by several years. Spare parts are available throughout the warranty period and for up to 5 years after the end of production. Upgradeability features contained in the product include: Intel LGA775 processor sockets 8 USB ports 1 PCI 32-bit/33MHz slot, 1 PCI-X slot and 5 PCI Express slots 8 expansion bays 8 - 16 memory slots, depending on configuration
Packaging Materials	
External	Cardboard carton and insert: 1.842 kg
Internal	LDPE Foam: ,592 kg
End-of-Life Management	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas.
and Recycling	To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
Hewlett-Packard	For more information about HP's commitment to the environment:
Corporate Environmental	[link to new HP white paper now in progress]
Information	Global Citizenship Report: http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications: http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html ISO 14001 certificates:



	http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html
Service, Support and Warranty	On-site Warranty and Service (Note 1): This three-year, limited warranty and service offering delivers three years of on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
	HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2002/95/EC. This product contains 0% recycled materials (by wt.)



Technical Specifications - Processors

Processors

Intel Xeon W5580, 3.20GHz, 8MB L3, 1333MHz Memory, 130W
Intel Xeon E5504, 2.00GHz, 4MB cache, 800MHz Memory, 4.80 GT/s QPI, 80W
Intel Xeon E5506, 2.13GHz, 4MB cache, 800MHz Memory, 4.80 GT/s QPI, 80W
Intel Xeon E5520, 2.26GHz, 8MB cache, 1066MHz Memory, 5.86 GT/s QPI, 80W
Intel Xeon E5530, 2.40GHz, 8MB cache, 1066MHz Memory, 5.86 GT/s QPI, 80W
Intel Xeon E5540, 2.53GHz, 8MB cache, 1066MHz Memory, 5.86 GT/s QPI, 80W
Intel Xeon X5550, 2.66GHz, 8MB cache, 1333MHz Memory, 6.40 GT/s QPI, 95W
Intel Xeon X5570, 2.93GHz, 8MB cache, 1333MHz Memory, 6.40 GT/s QPI, 95W
Intel Xeon X5570, 2.93GHz, 8MB cache, 1333MHz Memory, 6.40 GT/s QPI, 95W

Introduction

Intel's latest-generation microarchitecture represents the next step in unprecedented processor performance and dynamic scalability. Designed from the ground up to take advantage of hafnium-based Intel® 45nm hi-k metal gate silicon technology, Intel® Microarchitecture (Nehalem) unleashes parallel processing performance enabled by Intel® QuickPath technology providing an integrated memory controller and high-speed interconnect per independent processing core.

Performance and Features

Maximum multitasking performance Intel® Microarchitecture (Nehalem) offers the latest in processor innovation, including:

- Dynamic scalability, managed cores, threads, cache, interfaces, and power for energy-efficient performance on demand.
- Design and performance scalability for servers, workstations, notebooks and desktops with support for 2-8+ cores and up to 16+ threads with Intel® Hyper-Threading Technology (Intel® HT Technology), and scalable cache sizes, system interconnects, and integrated memory controllers.
- Intel® Turbo Boost Technology delivers additional performance automatically when needed by taking advantage of the processor's power and thermal headroom. This enables increased performance of both multi-threaded and single-threaded workloads.
- Intel Hyper-Threading Technology brings high-performance applications into mainstream computing with 1-16+ threads optimized for a new generation multi-core processor architecture.
- Scalable shared memory of Intel® QuickPath technology features memory distributed to each processor with integrated memory controllers and high-speed point-to-point interconnects to unleash the performance of future versions of next-aeneration Intel® multi-core processors.
- Multi-level shared cache improves performance and efficiency by reducing latency to frequently used data.

Turbo Boost Technology

This technology now built into Xeon 5500 processors will increase the speed of your processor on demand (from OS) if the CPU is operating below power / thermal specifications:

- Benefit of Turbo Boost (how much CPU speed up) depends on number of active cores
- Likelihood of Turbo Boost operation increases when less cores are active
- Likelihood of Turbo Boost operation increases when dynamic power mgt is enabled



Technical Specifications - Hard Drives

HP SAS (Serial Attached
SCSI) Hard Drives for HP
Workstations

300 GB (15K)

Capacity 300 GB
Height 1 in; 2.5 cm
Width Media Diam

Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.2 cm

Interface SAS
Synchronous Transfer 3.0 Gb/s
Rate (Maximum)

Buffer 16 MB

Seek Time (typical reads, includes controller overhead, including settling)Single Track overhead, including full Stroke0.2 msAverage overhead, including settling)Full Stroke6.7 ms

Rotational Speed 15,000 rpm

Logical Blocks 585,937,500 - 512 byte blocks Operating Temperature 50° to 95° F (10° to 35° C)

146 GB (15K) Capacity 146 GB
Height 1 in; 2.5 cm

 Width
 Media Diameter
 3.5 in; 8.9 cm

 Physical Size
 4 in; 10.2 cm

Interface SAS
Synchronous Transfer 3.0 Gb/s
Rate (Maximum)

Buffer 16 MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.2 msAverage
Full Stroke3.5 ms6.7 ms

Rotational Speed 15,000 rpm

Logical Blocks 86,749,488 - 512 byte blocks Operating Temperature 50° to 95° F (10° to 3°5 C)

 450 GB
 Capacity
 450 GB

 (15K)
 Height
 1 in; 2.5 cm

 Width
 Media Diameter
 3.5 in; 8.9 cm

 Physical Size
 4 in; 10.2 cm

Interface SAS
Synchronous Transfer 3.0 Gb/s
Rate (Maximum)

Buffer 16 MB

Technical Specifications - Hard Drives

Seek Time (typical reads, includes controller overhead, including settling)Single Track overhead, one o

Rotational Speed 15,000 rpm

Logical Blocks 879, 097, 968 - 512 byte blocks Operating Temperature 50° to 95° F (10° to 35° C)

SATA (Serial ATA) Hard 160,041,885,696

Drives for HP Workstations bytes (10K) **Capacity** 160,041,885,696 bytes

Height 1 in; 2.5 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.2 cm

Up to 150 MB/s

Interface Serial ATA (1.5 Gb/s), Native Command Queuing

enabled

Synchronous Transfer

Rate (Maximum)

Buffer

16 Mbytes

Seek Time (typical
reads, includes
controller overhead,
including settling)Single Track
Average0.3 msAverage
Full Stroke4.6 ms10.2 ms

Rotational Speed 10,000 rpm Logical Blocks 312,581,808

Operating Temperature 41 to 131 F (5 to 55 C)

1,000,204,886,016

bytes (7,200)

Capacity 1,000,204,886,016 bytes

Height 1 in; 2.5 cm

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.2 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing

enabled

Synchronous Transfer

Rate (Maximum)

Up to 300 MB/s

Buffer 32 MB

Seek Time (typical
reads, includes
controller overhead,
including settling)Single Track
Average2 msAverage
Full Stroke11 ms21 ms

Rotational Speed 7,200 rpm Logical Blocks 1,953,525,168

Operating Temperature 41 to 131 F (5 to 55 C)

500,107,862,016 Capacity 500,107,862,016 bytes



Technical Specifications - Hard Drives

bytes Height 1 in; 2.5 cm (7,200)

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.2 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing

enabled 300 MB/s

Synchronous Transfer

Rate (Maximum)

Buffer 16 MB

Seek Time (typical
reads, includes
controller overhead,
including settling)Single Track
Average2 msAverage
Full Stroke11 ms21 ms

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41 to 131 F (5 to 55 C)

250,059,350,016

bytes (7,200)

Capacity 250,059,350,016 bytes

Height 1 in; 2.5 cm

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.2 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing

enabled

Synchronous Transfer 300 MB/s

Rate (Maximum)

Buffer 16 MB

Seek Time (typicalSingle Track2 msreads, includes
controller overhead,
including settling)Average11 msFull Stroke21 ms

Rotational Speed 7,200 rpm Logical Blocks 488,397,168

Operating Temperature 41 to 131 F (5 to 55 C)

160,041,885,696

bytes (7,200)

Capacity 160,041,885,696 bytes

Height 1 in; 2.5 cm

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.2 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing

enabled

Synchronous Transfer 300 MB/s

Rate (Maximum)

Buffer 8 MB



Technical Specifications - Hard Drives

Seek Time (typicalSingle Track2 msreads, includes
controller overhead,
including settling)Average11 msFull Stroke21 ms

Rotational Speed 7,200 rpm Logical Blocks 312,581,808

Operating Temperature 41 to 131 F (5 to 55 C)

300,069,052,416

bytes (10K) **Capacity** 300,069,052,416 bytes

Height 0.6 in; 1.53 cm

Width Media Diameter 2.5 in; 6.36 cm

Physical Size 4 in; 10.17 cm

Interface Serial ATA (3.0Gb/s), Native Command Queuing

enabled

Synchronous Transfer

Rate (Maximum)

Up to 300 MB/s

Buffer 16 MB

Seek Time (typical Single Track 0.7 ms (maximum)

reads, includes controller overhead, including settling)

Average 4.4 ms

Full Stroke 9.5 ms

Rotational Speed 10,000 rpm Logical Blocks 586,072,368

Operating Temperature 41° to 131° F (5° to 55° C)

320,072,933,376

bytes (7,200)

Capacity 320,072,933,376 bytes

Height 0.98 in; 2.5 cm

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4.0 in; 10.17 cm

Interface Serial ATA (3.0 Gb/s), Native Command Queuing

enabled 300 MB/s

Synchronous Transfer

Rate (Maximum)

Buffer 8 MB

Seek Time (typical
reads, includes
controller overhead,
including settling)Single Track
Average2Full Stroke21

Rotational Speed 7,200 rpm Logical Blocks 625,142,448

Operating Temperature 41° to 131° F (5° to 55° C)

Technical Specifications - Hard Drive Controllers

Integrated SAS controller With RAID 0, 1/1E

PCI Bus PCI-Express x4 lanes
PCI Modes Bus Master DMA

RAID Levels RAID 0, 1, 1E and 10E

PCI Data Burst Transfer

Rate

250 MB/s per lane half duplex 500 MB/s per lane full duplex 1000 MB/s 4-lane half duplex

SAS Bandwidth Half Duplex Single lane – 300 MB/s

Wide Port (2 lanes) – 600 MB/s Wide Port (4 lanes) – 1200 MB/s

Full Duplex Single SAS Lane – 600 MB/s

Wide Port (2 lanes) –1200 MB/s Wide Port (4 lanes) – 2400 MB/s

PCI Card Type N/A
PCI Voltage N/A
PCI Power N/A
Bracket N/A

Certification Level PCI-Express 1.0a

IO Bus Eight 3Gb/s SAS/SATA ports

SAS Processor LSISAS1068E

Internal Connectors Four- SATA x1 connectors

External Connectors None Maximum Number of 122

SCSI Devices

LED Indicators
Integrated Mirroring

On-board activity and fault LEDs Integrated Mirroring option available

LSI MegaRAID® SAS 8888ELP Host Bus Adapter (HBA)

PCI Bus PCI-Express x8 lanes
PCI Modes Bus Master DMA
RAID Levels RAID 0, 1, and 5
RAID spans 10 and 50

PCI Data Burst Transfer

Rate

Up to 3Gb/s per port

Full Duplex Up to 1.5 GB/s
PCI Voltage +3.3V Add-in Card

PCI Power 7.5 Watts

Certification Level PCI-Express 1.0a

IO Bus Eight 3Gb/s SAS/SATA ports

Internal Connectors Two SAS SFF8087 x4
External Connectors Two SAS SFF8088 x4

Maximum Number of

SCSI DeviceS

32



Technical Specifications - Hard Drive Controllers

LED Indicators

Connector LEDs indicate whether the internal or external connector is active for ports 0-3 and 4-7



Technical Specifications - Graphics

ATI FirePro V3700 256MB Graphics Card Form Factor 4.40 inches (H) \times 6.70 inches (L) (11.18 cm (H) \times 17.02 cm (L))

Graphics Controller ATI FirePro V3700 Graphics Board Bus Type PCI Express x16, Generation 2.0

Memory 256 MB GDDR3 SDRAM unified graphics memory

Connectors 2 Dual Link DVI-I

Two DVI-I to VGA adapters included

Maximum Resolution Two dual-link DVI-I outputs drive two digital displays at resolutions up to

2560 x 1600 @ 60Hz or two analog displays at resolutions up to 2048 x

1536 @ 85Hz

Shading architecture Full Shader Model 4.0

• 40 Stream Processing Units

 Dynamic load balancing and resource allocation for vertex, geometry, and pixel shaders

 Common instruction set and texture unit access supported for all types of shaders

Dedicated branch execution units and texture address processors

Supported graphics APIs OpenGL 2.1

DirectX 10.1

Available graphics drivers Genuine Windows Vista Business (64-bit and 32-bit)

Microsoft Windows XP Professional (64-bit and 32-bit)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Linux drivers may be obtained from: http://ati.amd.com/support/driver.html

Power consumption 32 Watts

NVIDIA Quadro FX 380 256MB Graphics Card Form Factor 4.376 inches (H) \times 6.60 inches (L)

Graphics Controller NVIDIA Quadro FX 380 Graphics Board

Bus Type PCI Express x16, Generation 2.0

Memory 256 MB GDDR3 SDRAM unified graphics memory

Connectors 2 Dual Link DVI-I

Two DVI-I to VGA adapters included

Maximum Resolution Two dual-link DVI-I outputs drive two digital displays at resolutions up to

2560 x 1600 @ 60Hz or two analog displays at resolutions up to 2048 x

1536 @ 85Hz

RAMDAC Dual Internal 400 MHz DAC

Shading architecture Full Shader Model 4.0 (OpenGL 2.1/DirectX 10 class)

- Long fragment programs (unlimited instructions)
- Long vertex programs (unlimited instructions)
- Looping and subroutines (up to 256 loops per vertex program)
- Dynamic flow control



Technical Specifications - Graphics

Conditional execution

Supported graphics APIs

OpenGL 3.0 Direct X 10.0

Available graphics drivers Genuine Windows Vista Business(64-bit and 32-bit), Microsoft Windows XP

Professional(64-bit and 32-bit)

Red Hat Enterprise Linux(RHEL) WS4 & 5 Desktop/Workstation

HP qualified drivers may be preloaded or available from the HP support

Web site: http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from: ftp://download.nvidia.com/novell or http://www.nvidia.com

High-level Shader Languages

Optimized compiler for Cg and Microsoft HLSL

OpenGL 2.1 and DirectX 10 support

Open source compiler

CUDA™ Parallel **Processor Cores**

16

Power consumption

33.91 Watts

NVIDIA Quadro FX 580 512MB Graphics Card

Form Factor

4.376 inches (H) \times 6.60 inches (L)

Graphics Controller

NVIDIA Quadro FX 580 Graphics Board

Bus Type

PCI Express x16, Generation 2.0

Memory

512MB GDDR3 SDRAM unified graphics memory

Connectors

2 DisplayPort, 1 Dual-Link DVI-I.

One DisplayPort to DVI and one DVI to VGA adapter included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as an accessory)

Maximum Resolution

Two DisplayPort outputs drive two digital displays up to 2560 x 1600

One dual-link DVI-I output drives one digital display at resolutions up to 2560 x 1600 @ 60Hz or one analog display at resolutions up to

2048 x 1536 @ 85Hz

RAMDAC

Single Internal 400 MHz DAC

Shading architecture

Full Shader Model 4.0 (OpenGL 2.1/DirectX 10 class)

- Long fragment programs (unlimited instructions)
- Long vertex programs (unlimited instructions)
- Looping and subroutines (up to 256 loops per vertex program)
- Dynamic flow control
- Conditional execution

Supported graphics APIs

OpenGL 3.0

Direct X 10.0

Available graphics drivers Genuine Windows Vista Business(64-bit and 32-bit), Microsoft Windows XP

Professional(64-bit and 32-bit)

Red Hat Enterprise Linux(RHEL) WS4 & 5 Desktop/Workstation

HP qualified drivers may be preloaded or available from the HP support Web site:



Technical Specifications - Graphics

http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from: ftp://download.nvidia.com/novell or http://www.nvidia.com

High-level Shader Languages

Optimized compiler for Cg and Microsoft HLSL

OpenGL 2.1 and DirectX 10 support

Open source compiler

CUDA™ Parallel **Processor Cores**

Power consumption

40 Watts

32

NVIDIA Quadro FX 1800 Form Factor 768MB Graphics Card

4.376 inches (H) x 7.8 inches (L)

Graphics Controller NVIDIA Quadro FX 1800 Graphics Board

Bus Type PCI Express x16, Generation 2.0

Memory 768MB GDDR3 SDRAM unified graphics memory

Connectors 2 DisplayPort, 1 Dual-Link DVI-I.

One DisplayPort to DVI-D and one DVI to VGA adapter included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as an accessory)

Maximum Resolution

• Two DisplayPort outputs drive two digital displays up to 2560 x 1600

One dual-link DVI-I output drives one digital display at resolutions up to 2560 x 1600 @ 60Hz or one analog display at resolutions up to

2048 x 1536 @ 85Hz

RAMDAC

Single Internal 400 MHz DAC

Shading Architecture

Full Shader Model 4.0 (OpenGL 2.1/DirectX 10 class)

- Long fragment programs (unlimited instructions)
- Long vertex programs (unlimited instructions)
- Looping and subroutines (up to 256 loops per vertex program)
- Dynamic flow control
- Conditional execution

Supported Graphics APIs OpenGL 3.0

Direct X 10.0

Available Graphics Drivers

Genuine Windows Vista Business(64-bit and 32-bit), Microsoft Windows XP

Professional(64-bit and 32-bit)

Red Hat Enterprise Linux(RHEL) WS4 & 5 Desktop/Workstation

HP qualified drivers may be preloaded or available from the HP support Web site:

http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from: ftp://download.nvidia.com/novell or http://www.nvidia.com

High-level Shader Languages

Optimized compiler for Cg and Microsoft HLSL

OpenGL 2.1 and DirectX 10 support

Open source compiler



Technical Specifications - Graphics

CUDA™ Parallel **Processor Cores** 64.

Power consumption

59 Watts

ATI FirePro V5700 512MB Graphics Card

Form Factor

4.40 inches (H) \times 6.70 inches (L) (11.18 cm (H) \times 17.02 cm (L))

Graphics Controller Bus Type

ATI FirePro V5700 Graphics Board PCI Express x16, Generation 2.0

Memory

512 MB GDDR3 SDRAM unified graphics memory

Connectors

2 DisplayPort, 1 Dual-Link DVI-I.

One DisplayPort to DVI and one DVI to VGA adapter included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as

an accessory)

Maximum Resolution

• Two DisplayPort outputs drive two digital displays up to 2560 x 1600

• One dual-link DVI-I output drives one digital display at resolutions up to 2560 x 1600 @ 60Hz or one analog display at resolutions up to

2048 x 1536 @ 85Hz

Shading architecture

Full Shader Model 4.0

• 320 Stream Processing Units

Dynamic load balancing and resource allocation for vertex, geometry, and pixel shaders

Common instruction set and texture unit access supported for all types of shaders

Dedicated branch execution units and texture address processors

Supported graphics APIs

OpenGL 2.1 DirectX 10.1

Available graphics drivers Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Linux drivers may be obtained from: http://ati.amd.com/support/driver.html

Power consumption



Technical Specifications - Graphics

NVIDIA Quadro FX 3800 Form Factor

1.0GB Graphics Card

4.376 inches (H) x 9.0 inches (L)

Single slot card

Graphics Controller

NVIDIA Quadro FX 3800 Graphics Board

Bus Type

PCI Express x16, Generation 2.0

Memory

1GB GDDR3 SDRAM unified graphics memory

Connectors

2 DisplayPort, 1 Dual-Link DVI-I.

One DisplayPort to DVI-D and one DVI to VGA adapter included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as

an accessory)

Maximum Resolution

• Two DisplayPort outputs drive two digital displays up to 2560 x 1600

• One dual-link DVI-I output drives one digital display at resolutions up to 2560 x 1600 @ 60Hz or one analog display at resolutions up to

2048 x 1536 @ 85Hz

RAMDAC

Single Internal 400 MHz DAC

Shading architecture

Full Shader Model 4.0 (OpenGL 2.1/DirectX 10 class)

- Long fragment programs (unlimited instructions)
- Long vertex programs (unlimited instructions)
- Looping and subroutines (up to 256 loops per vertex program)
 - Dynamic flow control
- Conditional execution

Supported graphics APIs

OpenGL 3.0

Direct X 10.0

Available graphics drivers Genuine Windows Vista Business(64-bit and 32-bit), Microsoft Windows XP

Professional(64-bit and 32-bit)

Red Hat Enterprise Linux(RHEL) WS4 & 5 Desktop/Workstation

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from: ftp://download.nvidia.com/novell or http://www.nvidia.com

High-level Shader

Languages

Optimized compiler for Cg and Microsoft HLSL

OpenGL 2.1 and DirectX 10 support

Open source compiler

CUDA™ Parallel

Processor Cores

192

Power consumption

107.9 Watts



Technical Specifications - Graphics

NVIDIA Quadro FX 4800 Form Factor

1.5GB PCle Graphics Card

Graphics Controller

D. . T. . . .

Bus Type PCI Express x16, Generation 2.0

Memory 1.5 GB GDDR3 SDRAM unified graphics memory

4.36" (H) x 10.5" (L)

Dual slot card

Connectors 2 DisplayPort, 1 Dual-Link DVI-I, 1 3-pin Mini DIN stereo output, Two

NVIDIA Quadro FX 4800 graphics board

DisplayPort to DVI-D adapters included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as

an accessory)

Maximum Resolution ● 2 DisplayPort connectors support ultra-high-resolution panels (up to

2560 x 1600)

Dual-link DVI-I output drives one digital display at resolutions up to

2560 x 1600 @ 60Hz

Internal 400 MHz DACs-One analog display up to 2048 x 1536 @

85Hz

Full Shader Model 4.0 (OpenGL 2.1/DirectX 10 class)

• Long fragment programs (unlimited instructions)

Long vertex programs (unlimited instructions)

Looping and subroutines (up to 256 loops per vertex program)

Dynamic flow control

Conditional execution

Supported Graphics APIs OpenGL 3.0

Direct X 10.0

Available Graphics Drivers

Shading Architecture

Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit)

Red Hat Enterprise Linux(RHEL) WS4 & 5 Desktop/Workstation

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from: ftp://download.nvidia.com/novell or http://www.nvidia.com

High-Resolution AntiAliasing Rotated Grid Full-Scene Antialiasing (RG FSAA)

 32xFSAA dramatically reduces visual aliasing artifacts or "jaggies" at resolution up to 1920 x 1200

resolution up to 1920 x 1200

64x FSAA SLI Mode

High-level Shader Languages • Optimized compiler for Cg and Microsoft HLSL

OpenGL 2.1 and DirectX 10 support

Open source compiler

CUDA™ Parallel Processor Cores 192

Power consumption 1



Technical Specifications - Graphics

NVIDIA Quadro CX	N۷	/IDIA	Qua	dro CX
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Form Factor 4.36" (H) x 10.5" (L)

Dual slot card

Graphics Controller

NVIDIA Quadro CX 1.5GB Graphics Card

Bus Type

PCI Express x16, Generation 2.0

Memory Connectors 1.5 GB GDDR3 SDRAM unified graphics memory

2 DisplayPort, 1 Dual-Link DVI-I, 1 3-pin Mini DIN stereo output. Two DisplayPort to DVI-D adapters included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as

an accessory)

Maximum Resolution

• 2 DisplayPort connectors support ultra-high-resolution panels (up to

2560 x 1600)

 Dual-link DVI-I output drives one digital display at resolutions up to 2560 x 1600 @ 60Hz

2300 X 1000 @ 00HZ

• Internal 400 MHz DACs-One analog display up to 2048 x 1536 @

85Hz

RAMDAC

400MHz

Shading Architecture

• Full Shader Model 4.0 (OpenGL 2.1/DirectX 10 class)

Long fragment programs (unlimited instructions)

Long vertex programs (unlimited instructions)

Looping and subroutines (up to 256 loops per vertex program)

Dynamic flow control

Conditional execution

Supported Graphics APIs

OpenGL 3.0

Direct X 10.0

Available Graphics

Drivers

Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

High-Resolution AntiAliasing Rotated Grid Full-Scene Antialiasing (RG FSAA)

 32xFSAA dramatically reduces visual aliasing artifacts or "jaggies" at resolution up to 1920 x 1200

64x FSAA SLI Mode

High-level Shader Languages Optimized compiler for Cg and Microsoft HLSL

OpenGL 2.1 and DirectX 10 support

Open source compiler

CUDA™ Parallel Processor Cores 192

Power consumption

Technical Specifications - Graphics

NVIDIA Quadro FX 5800 Form Factor 4GB Graphics Card

4.36" (H) x 10.5" (L), Dual Slot

Graphics Controller

NVIDIA Quadro FX 5800 Graphics Board

Bus Type

PCI Express x16, Generation 2.0

Memory Connectors 4GB GDDR3 SDRAM unified graphics memory

2 Dual-Link DVI-I, 1 DisplayPort, 1 3-pin Mini DIN stereo output

Two DVI to VGA adapters included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as an accessory)

Maximum Resolution

• Two dual-link DVI-I outputs drive two digital displays at resolutions up to 2560 x 1600 @ 60Hz

One DisplayPort output drives an ultra-high-resolution panel (up to 2560 x 1600)

Internal 400 MHz DACs-Two analog displays up to 2048 x 1536 @ 85Hz

Shading Architecture

Full Shader Model 4.0 (OpenGL 2.1/DirectX 10 class)

Long fragment programs (unlimited instructions)

Long vertex programs (unlimited instructions)

Looping and subroutines (up to 256 loops per vertex program)

Dynamic flow control

Conditional execution

Supported Graphics APIs

OpenGL 3.0

Direct X 10.0

Available Graphics Drivers

Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit)

Red Hat Enterprise Linux(RHEL) WS4 & 5 Desktop/Workstation

HP qualified drivers may be preloaded or available from the HP support

Web site: http://welcome.hp.com/country/us/en/support.html

Novell SUSE Linux Enterprise drivers may be obtained from:

ftp://download.nvidia.com/novell or http://www.nvidia.com

High-Resolution AntiAliasing

Rotated Grid Full-Scene Antialiasing (RG FSAA)

32x FSAA dramatically reduces visual aliasing artifacts or "jaggies" at resolution up to 1920x1200

High-level Shader Languages

Optimized compiler for Cg and Microsoft HLSL

OpenGL 2.1 and DirectX 10 support

Open source compiler

CUDA™ Parallel **Processor Cores**

240

Power consumption



Technical Specifications - Graphics

ATI FirePro V7750 1.0GB Form Factor

Graphics Card

Graphics Controller

4.40 inches (H) \times 13.0 inches (L) (11.18 cm (H) \times 33.02 cm (L))

ATI FirePro V7750 Graphics Board **Bus Type** PCI Express x16, Generation 2.0

Memory 1024 MB GDDR3 SDRAM unified graphics memory

Connectors 2 DisplayPort, 1 Dual-Link DVI-I.

One DisplayPort to DVI and one DVI to VGA adapter included

('DisplayPort to VGA' and 'DisplayPort to Dual Link DVI' adapters available as

an accessory)

Maximum Resolution

• Two DisplayPort outputs drive two digital displays up to 2560 x 1600

One dual-link DVI-I output drives one digital display at resolutions up to 2560 x 1600 @ 60Hz or one analog display at resolutions up to

2048 x 1536 @ 85Hz

Shading architecture

Full Shader Model 4.0

• 320 Stream Processing Units

Dynamic load balancing and resource allocation for vertex, geometry, and pixel shaders

Common instruction set and texture unit access supported for all types of shaders

Dedicated branch execution units and texture address processors

Supported graphics APIs

OpenGL 2.1

DirectX 10.1

Available graphics drivers Genuine Windows Vista Business (64-bit and 32-bit) Microsoft Windows XP Professional (64-bit and 32-bit)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Linux drivers may be obtained from: http://ati.amd.com/support/driver.html

Power consumption 76 Watts

Technical Specifications - Multimedia and Audio Devices

Integrated Intel/Realtek HD ALC262 Audio

Integrated Type

High Definition Codec Yes FM Synthesis Support Yes **OPL3 FM Synthesis** Yes

Support

Sound Blaster Yes

Compatibility

Meets Premium Yes performance for Windows Logo Program 3.0

Audio Jacks Front panel microphone in and headphone out - fixed usage.

Rear panel line in and line out jacks - jacks are retaskable

One Line-In* (12-K ohm Input Impedance)*

NOTE: External Speakers need to be powered externally.

Sampling 3 stereo ADCs support 16/20-bit PCM format with 44.1K/48K/96kHz

sample rate

2 stereo DAC supports 16/20/24-bit PCM format with

44.1K/48K/96K/192kHz sample rate

Wavetable Syntheses

(software)

Yes – GM and FM Midi Support, Direct Music and Down Loadable Soundset

(4 Meg DLS Level 1 and 2 Support)

3D Positional Sound No Digital Audio Yes **Analog Audio** Yes **DVD** Audio Yes

Number of Channels on

Line-Out

Stereo (Left & Right channels)

Internal Audio Speaker

Power Rating

1.5 W

Internal Speaker Hardware Equalizer for

Yes No

Internal Speaker

External Speaker Jack

Yes

(Line-Out)

Technical Specifications - Multimedia and Audio Devices

SoundBlaster (Creative Labs) X-Fi Titanium PCle Audio Card

24-bit Analog-to-Digital

conversion of analog

inputs

24-bit Digital-to-Analog

conversion of digital

sources

96kHz sample rate

24-bit Digital-to-Analog conversion of stereo digital sources

16-bit to 24-bit recording 16-bit/44.1kHz, 16-bit/48kHz, 24-bit/44.1kHz, 24-bit/48kHz and 24-

8, 11.025, 16, 22.05, 24, 32, 44.1, 48 and 96kHz

96kHz to analog 7:1 speaker output

sampling rates bit/96kHz with direct monitoring

Enhanced SoundFont Up to 24-bit resolution

109dB

support

Signal-to-Noise Ratio

(2okHz Low-pass filter, A-

Weighted)

Total Harmonic Distortion .004%

+ Noise at 1kHz (20kHz

Low-pass filter)

Frequency Response (-

3dB, 24-bit/96kHz input)

10Hz to 46kHz

Frequency Response (-10Hz to 46kHz

3dB, 24-bit/192kHz input)

connections

Speaker and Headphone Stereo to 7.1 (Line Out via three 3.5mm mini jacks)

Flexijack Line In/ Microphone In/Optical Out via shared 3.5mm mini jack Front Panel Header Intel HD Audio Compatible (2x5 pin)

Operating System Microsoft Windows Vista Business 64

Microsoft Windows Vista Business 32 Microsoft® Windows® XP Professional SP2

Microsoft Windows XP Professional x64 Edition

512MB Minimum System System RAM

Requirements Windows Vista 32-bit and 64-bit version or Operating System

Windows XP 32-bit or 64-bit version

Technical Specifications - Optical and Removable Storage

NOTE: Actual speeds may vary. Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Н	РΙ	D١	/D	-R	\circ	м	D	riv	•

5.25-inch, half-height, tray-load Description Mounting Orientation Either horizontal or vertical

SATA/ATAPI Interface Type

Dimensions (WxHxD) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB Double layer: Up to

8.5 GB

Access Times DVD-ROM Single Layer < 140 ms (typical)

> CD-ROM Mode 1 < 125 ms (typical) Full Stroke DVD < 250 ms (seek) Full Stroke CD < 210 ms (seek)

Power Source SATA DC power receptacle

> DC Power Requirements $5 \text{ VDC} \pm 5\%\text{-}100 \text{ mV ripple p-p}$

> > 12 VDC ± 5%-200 mV ripple p-p

DC Current 5 VDC - < 1000 mA typical, < 1600 mA

maximum

12 VDC - < 600 mA typical, < 1400 mA

maximum

Operating Environmental Temperature

(all conditions noncondensing)

Relative Humidity Maximum Wet Bulb

Temperature

Operating Systems

Supported

41° to 122° F (5° to 50° C)

10% to 90%

86° F (30° C)

Windows Vista Business 64* Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or

Windows XP Home 32*.

Red Hat Enterprise Linux(RHEL) WS3, WS4, 5

Desktop/Workstation Novell SLES 9 & SLE 10

No driver is required for this device. Native support is provided by the operating system.

* Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit:

http://www.windowsvista.com/

upgradeadvisor. For Windows Vista system

requirements, visit:

http://www.windowsvista.com/

systemrequirements.



Technical Specifications - Optical and Removable Storage

HP DVD+/-RW Drive	Description	5.25-inch, half-height, tray-load
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Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)

Disc Formats DVD-RAM

> DVD+RDVD+RWDVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

> Full Stroke DVD < 250 ms (seek) Full Stroke CD < 210 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 40X

CD-RW Up to 32X

DVD ROM Read DVD-RAM Up to 12X

> DVD+RWUp to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 16X DVD-ROM DL Up to 8X DVD+RUp to 16X DVD-R Up to 16X

Power Source SATA DC power receptacle

> DC Power Requirements $5 \text{ VDC} \pm 5\%\text{-}100 \text{ mV ripple p-p}$

 $12 \text{ VDC} \pm 5\%$ -200 mV ripple p-p

DC Current 5 VDC -1000 mA typical, 1600 mA maximum

12 VDC -600 mA typical, 1400 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity Maximum Wet Bulb **Temperature**

10% to 90% 86° F (30° C)

Operating Systems

Supported

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*,

Windows 2000, Windows XP Professional or

Windows XP Home 32*.

Red Hat Enterprise Linux(RHEL) WS3, WS4, 5

Desktop/Workstation Novell SLES 9 & SLE 10

No driver is required for this device. Native



Technical Specifications - Optical and Removable Storage

support is provided by the operating system.

* Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor. For Windows Vista system requirements, visit: http://www.windowsvista.com/

nπp://www.windowsvista.coi

* LightScribe functionality is not natively supported by Linux distributions. Customers may download LightScribe Linux drivers from: http://www.lightscribe.com/

http://www.lightscribe.com/downloadSection/linux/index.aspx

Kit Contents HP SATA SuperMulti LightScribe DVD Writer drive,

LightScribe software, Roxio Easy Media Creator software, Intervideo WinDVD Software, installation

guide, and DVD+R media.

HP Slot Load DVD+/-RW Description

Drive

escription Slim-Line, Slot-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA

Dimensions (WxHxD) 5 x .5 x 5 in (12.7 x 1.2 x 12.9 cm) 0

Disc Formats DVD-RAM DVD+R DVD+R DVD+R DL DVD-R DL DVD-R DVD-RW CD-R

CD-RW

Disc Capacity DVD-ROM 5/9/10/18 G DVD-Single / Dual (PTP, OTP)

(Read Only)

4.7G DVD±R/RW (Read & Write)
DVD±R Dual (Read & Write)

80mm DVD

DVD-RAM (Read & Write)

CD-ROM 650 MB CD-ROM (Read Only)

80mm CD

800/700/650/ CD-Recordable (Read & Write) 700/650MB CD-Rewritable (Read & Write) 700/650MB High Speed CD-Rewritable (Read &

Write)

700/650MB Ultra & Ultra+ Speed CD-

Rewritable (Read & Write)

Full Stroke DVD < 270 ms (seek) Full Stroke CD < 250 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read DVD ROM Read

CD-ROM, CD-R and CD-RW Up to 24X
DVD-RAM Up to 5X DVD Single layer Up to 8X

DVD Dual Layer up to 6X



Technical Specifications - Optical and Removable Storage

Power	Source	SATA DC power receptacle
	DC Power Requirements	5 VDC \pm 5%-100 mV ripple p-p
	DC Current	5 VDC 40 mA typical, 800 mA maximum
Operating Environmental	Temperature	41° to 122° F (5° to 50° C)
(all conditions non-	Relative Humidity	10% to 90%
condensing)	Operating Systems Supported	Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows XP Professional or Windows XP Home 32*. Red Hat Enterprise Linux(RHEL) WS3, WS4, 5 Desktop/Workstation Novell SLES 9 & SLE 10 No driver is required for this device. Native support is provided by the operating system.
	Kit Contents	Factory integrated only. Not available as a kit.

HΡ	Blu-	-Ray	W	riter
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Description	5.25-inch, half-height, tray-load
Mounting Orientation	Fither horizontal or vertical

SATA

Interface Type

Dimensions (WxHxD) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)

Disc Formats

BD-ROM BD-R BD-RE DVD-RAM DVD+RDVD+RWDVD+R DL DVD-R DL

DVD-R DVD-RW CD-R CD-RW

Disc Capacity

DVD-ROM 8.5 GB DL or 4.7 GB standard

50 GB DL or 25 GB standard Blu-ray

Full Stroke DVD < 250 ms (seek) Full Stroke CD < 210 ms (seek)

Blu-ray Blu-ray

Startup Time (Time to drive ready from tray

loading)

BD-ROM (SL/DL) 25\$ / 28\$ BD-R (SL/DL) 25\$ / 28\$ BD-RE (SL/DL) 25\$ / 28\$ DVD-ROM (SL/DL) 185 / 185 25\$ / 25\$ DVD-R (SL/DL) DVD-RW **25S** DVD+R (SL/DL) 25S / 25S DVD+RW**25S**



Technical Specifications - Optical and Removable Storage

		DVD-RAM	45\$	
		CD-ROM 45S		
Maximum Data Transfer	CD ROM Read	CD-ROM	Up to 40X	
Rates		CD-R	Up to 40X	
		CD-RW	Up to 40X	
	DVD ROM Read	DVD-RAM	Up to 5X	
		DVD+RW	Up to 10X	
		DVD-RW	Up to 10X	
		DVD+R DL	Up to 8X	
		DVD-R DL	Up to 8X	
		DVD-ROM	Up to 16X	
		DVD-ROM DL	Up to 8X	
		DVD+R	Up to 12X	
		DVD-R	Up to 12X	
	Blu-Ray	BD-ROM	Up to 6X	
		BD-ROM DL	Up to 4.8X	
		BD-R	Up to 6X	
		BD-R DL	Up to 4.8X	
		BD-R	Up to 6X	
		BD-RE SL/DL	Up to 4.8X	
Power	Source	SATA DC power receptacle		
	DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p 12 VDC ± 10%-100 mV ripple p-p		
	DC Current	5 VDC -900 mA typical, 1200 mA maximum 12 VDC -1000 mA typical, 1600 mA maximu		
Operating Environmental	Temperature	41° to 122° F (5° to 50° C)		
(all conditions non-	Relative Humidity	15% to 80%		
condensing)	Maximum Wet Bulb Temperature	86° F (30° C)		
	Operating Systems Supported	Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP Home 32*. Red Hat Enterprise Linux(RHEL) WS3, WS4, 5 Desktop/Workstation Novell SLES 9 & SLE 10		
	Kit Contents	No driver is required for this device. Native support is provided by the operating system. HP Blue Laser RW Drive, LightScribe software, Roxio Easy Media Creator software, Intervideo WinDVD Software, installation guide.		



Technical Specifications - Optical and Removable Storage

Disclaimer As Bl

As Blu-Ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-Ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support.

HD-DVD movies cannot be played on this workstation.

HP 22-in-1 Media Card

Reader

Description The Media Card Reader device uses the same physical form factor and

mounting as a Floppy Disk Drive. The device connects to a 2x5 two-channel USB header on the motherboard of the system. There is no USB controller card provided. Please see the Disc Formats section below for a list of flash

memory card formats that are supported.

Mounting Orientation The Media Card Reader can be mounted in a dedicated Floppy Drive bay (if

the chassis provides one) or in an appropriate Optical Bay adapter. It will

operate in any orientation.

Interface Type USB 2.0 (one channel dedicated to the separate USB port; one channel

dedicated to the flash memory card slots)

Dimensions (WxHxD)

4.9 x 4.0 x 1.0 in (124.5 x 101.6 x 25.4 mm)

Disc Formats

xD-Picture Micro SD

Micro SDHC

SD SDHC Mini SD Mini SDHC

MultiMediaCard (MMC)

Reduced Size MultiMediaCard (RS MMC)

MultiMedia Card 4.2 (MMC Plus, including MMC Plus HC)

Reduced Size MultiMedia Card 4.2 (MMC Mobile, including MMC Mobile

HC)

CompactFlash Card Type I CompactFlash Card Type II

MicroDrive Memory Stick (MS)

MagicGate Memory Stick (MG) MagicGate Memory Stick Duo

Memory Stick Select

Memory Stick Duo (MS Duo) Memory Stick PRO (MS PRO)

Memory Stick PRO Duo (MS PRO Duo)

Memory Stick PRO-HG Duo

Two additional formats are usable with adapters (not supplied):

MMC Micro

Memory Stick Micro (M2)



Technical Specifications - Optical and Removable Storage

HP DX115 Removable Drive Enclosure

Interface Type Compatible with SAS or SATA controllers

Dimensions (WxHxL) 5.81 x 1.62 x 8.08 in (147.6 x 41.1 x 205 mm) Weight

Frame and Carrier: 3.8 lbs (1.73 kg)

Carrier: 1 lbs (0.45 kg)



Technical Specifications - Controller Cards

HP IEEE 1394b FireWire

PCIe Card

Data Transfer RateSupports up to 800 MbpsDevices SupportedIEEE-1394 compliant devicesBus TypePCle card full height PCle slots

Ports Two IEEE-1394b bilingual 9-Pin Connector (Rear)

Internal Connectors One 10-Pin header Custom Connector

System Requirements Microsoft Windows XP Professional, Windows XP Home, Windows Vista. Not

supported on Linux. Pentium® III or higher processor 128-MB RAM 1-GB

Hard Drive CD-ROM drive Built in sound system Available PCI slot

Temperature – Operating 50° to 131° F (10° to 55° C)

Temperature – Storage -22° to 140° F (-30° to 60° C)

Relative Humidity –

Operating

20% to 80%

Compliances FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998

STD, Taiwan BSMI CNS13438, Korea MIC

Operating Systems

Supported

Microsoft Windows XP and Windows Vista



Technical Specifications - Networking and Communications

NOTE: "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Integrated Broadcom 5764 PCle LOM Controller Connector RJ45

10/100/1000BT

Bus Architecture

Data Rates Supported

PCle X1

ASF 2.0

Alerting

Broadcom (5761) NetXtreme Gigabit Ethernet Plus NIC Connector RJ-45

Controller Broadcom 5761 PCI-Express LAN Controller

Memory 8 MB NVRAM serial Flash

Data Rates Supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB, 802.3u, and 802.3x

Bus Architecture PCI-Express

Data Path Width Single Channel PCI-Express

Data Transfer Mode Bus Master DMA

Hardware Certifications FCC class B, Canada and US NRTL Mark, C-Tick for Australia, BSMI for

Taiwan, VCCI for Japan, MIC for Korea, GOST for Russia, UL listed

(E212044), European Union Notice (CE 0682)

Power Requirement 1.8W @ 3.3V

Boot ROM Support Yes

Network Transfer Mode Full-duplex

Half-duplex (not available for the 1000BASE-T transceiver)

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating Temperature 32° to 131°F (0° to 55° C)

Operating Humidity 131° F (55° C) with 5% to 95% non-condensing humidity

Dimensions 2.75 in x 4.13 in (7 cm x 10.5 cm), low profile compatible

Operating System Driver Windows Vista 32-bit SP1, Windows Vista x64 SP1, Windows XP 32 bit

Support professional, Windows XP x64.

Management Capabilities ACPI, WOL and DMI 2.0, PXE 2.0, WfM 2.0, Broadcom mgmt utility,

ASF2.0, DASH 1.0 and DASH 1.1 profiles

Kit Contents Broadcom NetXtreme Gigabit Ethernet Plus NIC, Broadcom NetXtreme

Gigabit Ethernet Plus NIC USB Cable Assembly, CD, drivers, quick install

guide, product warranty statement

Technical Specifications - Networking and Communications

HP NC360T PCI Express Dual Port Gigabit NIC Connector Two RJ-45
Controller Intel 82571EB
Memory Integrated 96KB
Data Rates Supported 10/100/1000 Mbps

Compliance 802.3, 802.3u, 802.3x, 802.3ab, 802.3ad, 802.1p, 802.1Q

Bus Architecture PCI-E 1.0a

Data Path Width Four lane (x4) PCI Express compatible with x4, x8, and x16 PCI Express slots

Data Transfer Mode Bus-master DMA

Hardware Certifications FCC Class B, VCCI Class B, BSMI Class A, CISPR 22 Class B, EN 55022

Class B, EN55024-1, ICES-003 Class B, MIC Class B, ACA Class B, UL,

Canada UL, EN60950

Power Requirement 1280 mA @ 3.3V typical

Boot ROM Support Yes

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating Temperature 32° to 131° F (0° to 55° C)
Operating Humidity 0% to 95% non-condensing
Dimensions 5.1×2.7 in $(12.95 \times 6.8 \text{ cm})$

Operating System Driver

Support

Windows Vista Business 64*, Windows Vista Business 32*, Windows XP

Professional, Windows XP Professional x64 Edition.

Red Hat Enterprise Linux(RHEL) WS4, 5 Desktop/Workstation

Novell SLES 9 & SLE 10

* Certain Windows Vista product features require advanced or additional hardware. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor. For Windows Vista

system requirements, visit:

http://www.windowsvista.com/systemrequirements.

Management Capabilities WOL, PXE 2.1

Kit Contents HP NC360T PCI Express Dual Port Gigabit NIC, low profile bracket, CD

containing Intel PROset II NIC drivers, quick install guide, product warranty

statement



Technical Specifications - Networking and Communications

Intel Gigabit CT Desktop Connector

NIC

Connector RJ-45

Controller Intel WG82574L Gigabit Ethernet Controller

Memory Integrated Dual 48K configurable transmit receive FIFO Buffers

Data Rates Supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB and 802.3u compliant,

802.3x flow control

Bus Architecture PCI-E 1.0a

Data Path Width X1, 250 MB/s, Bi-directional interface

Data Transfer Mode Bus-master DMA

Hardware Certifications FCC, B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS Mark

for European Union

Power Requirement Aux 3.3V, 3.0 Watts in 1000base-T and 2.0 Watts in 100Base-T

Boot ROM Support Yes

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating Temperature 32° to 131°F (0° to 55° C)
Operating Humidity 85% at 131° F (55° C)

Dimensions 4.75 x 2.25 x 0.8 in (12.1 x 5.7 x 2.0 cm)

Operating System Driver

Support

Windows Vista Business 64, Windows Vista Business 32, Windows XP

Professional, Windows XP x64.

Red Hat Enterprise Linux 4, Red Hat Enterprise Linux 5.

Management Capabilities WOL , PXE, DMI, WFM 2.0

Kit Contents Intel Gigabit CT Desktop NIC, low profile bracket, CD containing Intel

PROset II NIC drivers, quick install guide, product warranty statement

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